PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Feng Wei Kuo	02/25/2013
Kuang-Kai Yen	02/25/2013
Huan-Neng Chen	02/25/2013
Hsien-Yuan Liao	02/24/2013
Lee Tsung Hsiung	02/25/2013
Chewn-Pu Jou	02/25/2013
Robert Bogdan Staszewski	02/24/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Co., Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Hsin-Chu Science Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13778478

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CORRESPONDENCE DATA

Fax Number: 2165020601
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 212-502-0600
Email: docketing@eschweilerlaw.com
Correspondent Name: Eschweiler & Associates, LLC.
Address Line 1: 629 Euclid Avenue, Suite 1000
Address Line 2: National City Bank Building
Address Line 4: Cleveland, OHIO 44114

ATTORNEY DOCKET NUMBER:	TSMCP235US
NAME OF SUBMITTER:	Thomas G. Eschweiler

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TSMC Docket No. TSMC2012-1235

U.S. Patent Appln. No.

Docket No. TSMCP235US

Filing Date

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Feng Wei Kuo
No.12, Aly. 10, Ln. 289, Xuefu E. Rd.
Hsinchu County
Zhudong Township 310
Taiwan (R.O.C.)

Assignor(s):
Kuang-Kai Yen
11F., No.2, Ruicheng St.
Qianzhen Dist.
Kaohsiung City 806
Taiwan (R.O.C.)

Assignor(s):
Huan-Neng Chen
No.10-1, Zhongqi Rd.
Shalu Dist.
Taichung City 433
Taiwan (R.O.C.)

Assignor(s):
Hsien-Yuan Liao
No.516, Sec. 2, Zhangyuan Rd.
Changhua County
Huatan Township 503
Taiwan (R.O.C.)

Assignor(s):
Lee Tsung Hsiung
3F., No.9, Aly. 2, Ln. 451, Qingyun Rd.
Tucheng Dist.
New Taipei City 236
Taiwan (R.O.C.)

Assignor(s):
Chewn-Pu Jou
No.46, Ln.71, Chung-Hsiao St.
Chutung
Hsinchu
Taiwan (R.O.C.)

U.S. Patent Appln. No. Docket No. TSMCP235US

Filing Date

Assignor(s):
Robert Bogdan Staszewski
Raad van Europalaan 23
2625 PA DELFT
The Netherlands

Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled **"PVT-FREE CALIBRATION CIRCUIT FOR TDC RESOLUTION IN ADPLL"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. ________________________,

filed on ________________________.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

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Filing Date

2013.02.25
Date

Feng Wei Kuo
Name 1st Inventor Feng Wei Kuo

2013.02.25
Date

Kuang-Kai Yen
Name 2nd Inventor Kuang-Kai Yen

U.S. Patent Appln. No.

Filing Date

2013.02.25

Date

Huan Neng Chen

Name 3rd Inventor Huan-Neng Chen

2013.02.24
Date

Hsien-Yuan Liao
Name 4th Inventor Hsien-Yuan Liao

U.S. Patent Appln. No.
Filing Date

2012. 7. 25
Date

Lee Tsung Hsiung
Name 5th Inventor Lee Tsung Hsiung

2013 Feb 25
Date

Name 6th Inventor Chewn-Pu Jou

2013-02-24

Date

Name 7th Inventor Robert Bogdan Staszewski